

CHEMTRONICS® Technical Data Sheet

TDS # SWPbFree

Soder-Wick® Lead-Free SD Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® Lead-Free is the state of the art in desoldering technology. It is specially designed for removal of today's high temperature lead-free solders. The single layer weave used for Soder-Wick® Lead-Free braid is lighter in mass than any other desoldering braid available and allows for lead-free solder removal at lower temperatures. Soder-Wick® Lead-Free responds faster than any other conventional desoldering braid. This unique design minimizes overheating and requires less "contact" time thus preventing heat damage to the PCB and sensitive components. For Lead-Free rework, Soder-Wick® has the answer.

- Fastest wicking and heat transfer
- High capacity for solder uptake
- Halide free, no corrosive residues
- Minimizes risk of heat damage to pads, components and PCBs
- Can be used with Tin/Lead solders
- RoHS compliant

TYPICAL APPLICATIONS

Soder-Wick® Lead-Free desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals, Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Flux Type	High-Temperature No Clean Type ROL0
Specifications:	ANSI/IPC J STD-004 MIL-F-14256 F
No Clean Flux Spec:	MIL-STD-883B Bellcore TR-NWT-000078 ANSI/IPC J SF818
Shelflife:	2 years

Size #	Width Inches	Color	Width Metric
2	.060"	Yellow	1.5 mm
3	.080"	Green	2.0 mm
4	.110"	Blue	2.8 mm

STATIC DISSIPATIVE PACKAGING

Soder-Wick® Lead-Free is packaged on Static Dissipative bobbins to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B and meet the static delay rate provision of MIL-B-81705C.

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick® Lead-Free braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 650° and 750°F
- 4) Place wick on solder joint or pad and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks® Lead-Free Flux Remover Pen CW9400 and remove soils with a ControlWipes™ absorbent wipe.

SODER-WICK® IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R

NASA-STD-8739.3

DOD-STD-883E, Method 2022

ANSI/IPC J STD-004, Type ROL0

BELLCORE TR-NWT-000078

ANSI/IPC J SF-818

SODER-WICK® SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A

MIL-B-81705C

MIL-STD-1686C

MIL-HDBK-263B

AVAILABILITY

40 Series

Lead-Free No Clean Flux

25 bobbins / bag

Part #		Size
5 feet	10 feet	
40-2-5	40-2-10	2
40-3-5	40-3-10	3
40-4-5	40-4-10	4

<i>VacuPak™ Packaging</i>	Part #	Size
The VacuPak™ Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.	SW14025	2
	SW14035	3
	SW14045	4

NOTE: This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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